

L Number	Hits	Search Text	DB	Time stamp
1	553	((frame structure base layer film) near4 silicon\$2) and (silicon\$2 near4 nitride) and (heat\$4 therm\$5) and (insulat\$5 imperm\$6 seal\$5) and ( diaphragm membrane) and (((temperat\$5 heat thermal) near2 sens\$4) or thermometer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/14 14:52
8	332	((frame structure base layer film) near4 silicon\$2) and (silicon\$2 near4 nitride) and (heat\$4 therm\$5) and (insulat\$5 imperm\$6 seal\$5) and ( diaphragm membrane) and (((temperat\$5 heat thermal) near2 sens\$4) or thermometer)) and ((sens\$4 measur\$4 determin\$4 estimat\$4 detect\$4) near4 (flow volume mass))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/14 15:13
15	95	(((frame structure base layer film) near4 silicon\$2) and (silicon\$2 near4 nitride) and (heat\$4 therm\$5) and (insulat\$5 imperm\$6 seal\$5) and ( diaphragm membrane) and (((temperat\$5 heat thermal) near2 sens\$4) or thermometer)) and ((sens\$4 measur\$4 determin\$4 estimat\$4 detect\$4) near4 (flow volume mass))) and 73/\$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/14 15:13
	279	73/204.26.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/25 10:40
	9	("5423212" "5393351" "5703287").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 17:06
	200	73/204.26.ccls. and (membrane coat\$4 layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 17:19
	1	73/204.26.ccls. and (membrane coat\$4 layer) and impermeable	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 17:19
	2	("4682503"   "4766666").PN.	USPAT	2002/01/24 17:20
	27	4766666.URPN.	USPAT	2002/01/24 17:20
	64	73/204.26.ccls. and silicon and nitride	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 18:05
	58	73/204.26.ccls. and silicon and nitride and (heat\$4 therm\$5) and (insulat\$5 imperm\$6 membrane)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 18:20
	55	73/204.26.ccls. and silicon and nitride and (heat\$4 therm\$5) and (insulat\$5 imperm\$6 membrane) and (temperat\$5 near2 (sens\$4 measur\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/25 15:21
	17	73/204.26.ccls. and silicon and nitride and (heat\$4 therm\$5) and (insulat\$5 imperm\$6 seal\$5) and membrane and (temperat\$5 near2 (sens\$4 measur\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 19:03
	15	73/204.26.ccls. and silicon and nitride and (heat\$4 therm\$5) and (insulat\$5 imperm\$6 seal\$5) and membrane and (temperat\$5 near2 (sens\$4 measur\$6)) and (contact terminal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 20:35

	14	73/204.26.ccls. and silicon and nitride and (heat\$4 therm\$5) and (insulat\$5 imperm\$6 seal\$5) and membrane and (temperat\$5 near2 sens\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/14 14:20
	3	73/204.26.ccls. and carbide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 20:36
	25	("5393351" "5852239" "5423212" "5703287" "6318170" "6290388" "6240777" "5965813" "4682503" "4545650").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/25 10:42
	4	(("si.sub.3.n.sub.4.") or (silicon? near2 nitride)) and (heat\$4 therm\$5) and ((no? near3 permea\$4) imperm\$6) and (temperat\$5 near2 (sens\$4 detect\$4 determin\$4 meter\$4 measur\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/25 15:44
	0	"si.sub.3.n.sub.4."	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/25 15:46
	1	"si.sub.3-n.sub.4"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/25 15:49
17387		"si.sub.3 n.sub.4"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/25 15:49
	51	("si.sub.3 n.sub.4" or (silicon? near2 nitride)) and ((no? near3 permea\$4) imperm\$6) and (temperat\$5 near2 (sens\$4 detect\$4 determin\$4 meter\$4 measur\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/25 16:52
	4	("si.sub.3 n.sub.4" or (silicon? near2 nitride)) same ((no? near3 permea\$4) imperm\$6) and (temperat\$5 near2 (sens\$4 detect\$4 determin\$4 meter\$4 measur\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/25 15:58
	6	("si.sub.3 n.sub.4" or (silicon? near2 nitride)) same ((no? near3 permea\$4) imperm\$6) and ((temperat\$5 heat) near2 (sens\$4 detect\$4 determin\$4 meter\$4 measur\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/25 16:19
	64	("si.sub.3 n.sub.4" or (silicon? near2 nitride)) and ((water near2 repel\$5) or (no? near3 permea\$4) or impermea\$6) and (temperat\$5 near2 (sens\$4 detect\$4 determin\$4 meter\$4 measur\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/25 16:15
	17	(("si.sub.3 n.sub.4" or (silicon? near2 nitride)) and ((water near2 repel\$5) or (no? near3 permea\$4) or impermea\$6) and (temperat\$5 near2 (sens\$4 detect\$4 determin\$4 meter\$4 measur\$6))) and sandw\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/25 16:15

	17	("si o.sub.2" or (silicon? near2 oxide)) near6 (recess hole hollow cavity gap)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/25 16:54
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